L Number	Hits	Search Text	DB	Time stamp
1	227	HEAT ADJ CONDUCTIVE ADJ BASE	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/08 15:19
2	2	(HEAT ADJ CONDUCTIVE ADJ BASE) AND HEAT ADJ INSULATING ADJ COVER	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/08 15:20
3	61	(HEAT ADJ CONDUCTIVE ADJ BASE) AND COVER	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/08 15:23
4	33	(HEAT ADJ CONDUCTIVE ADJ BASE) AND SEALED	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/08 15:25
5	8	(HEAT ADJ CONDUCTIVE ADJ BASE) AND MATE	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/08 15:26